Huawei Ascend 910C

Da Vinci v2 (dual-die) | OAM | 2025 | SMIC 7nm

OVERVIEW

50.0	128 GB	3.2 TB/s	600 W
FP32 TFLOPS	VRAM HBM2e	Memory Bandwidth	TDP

PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
INT8	1600.0	8	Standard
FP16	800.0	16	Standard
BF16	780.0	16	Standard
FP32	50.0	32	Standard

MEMORY SPECIFICATIONS

Capacity	128 GB
Type	HBM2e
Bandwidth	3.2 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	600 W
Est. Max Power	690 W
FP32 Efficiency	0.08 TFLOPS/W
FP16 Efficiency	1.33 TFLOPS/W

HARDWARE DETAILS

Vendor: Huawei

Architecture: Da Vinci v2 (dual-die)

Process Node: SMIC 7nm

Form Factor: OAM

Launch Year: 2025

INTERCONNECT

GPU-to-GPU: Unified Bus (UB)

Bandwidth: 350 GB/s